



—Quick-press processable—
Adhesive sheet **“AE91M”**

Example of use

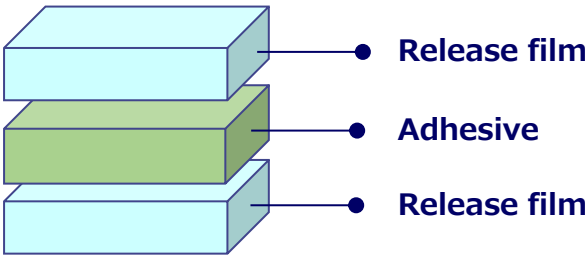
- Smartphone
- Tablet PC
- Laptop computer



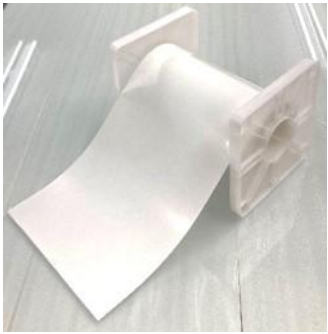
Characteristics

- Good circuit-filling by quick-press.
- High performance in ion migration suppression with frame retardancy equivalent to V-0 (UL94).

Product structure



Appearance

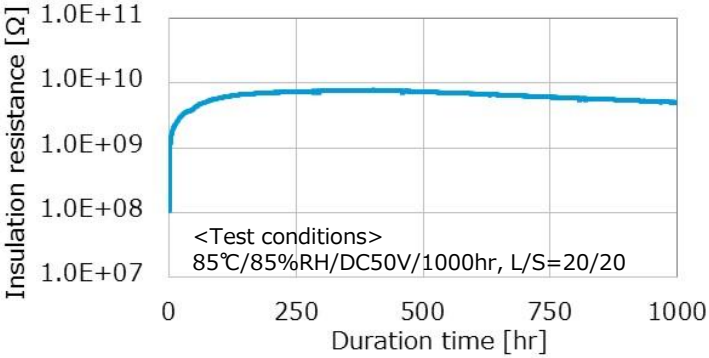


Product Properties

Item	Unit	AE91M
90° Peel strength (Peeling 1mil/1oz FCCL)	N/cm	16
Solder heat resistance	℃	310
Flammability	—	Equivalent to V-0
Circuit filling by quick-press (185℃)	-	60 sec.
HHBT	—	> 1000hr
Tg	℃	80
Elastic modulus	GPa	1.3

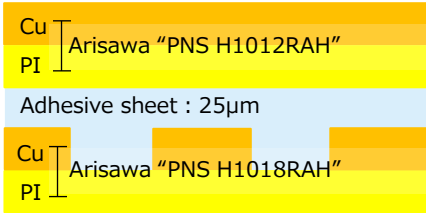
Sample making conditions (pressing) :
160℃×3MPa×Keep 45min.

<Ion migration resistance>



<Test sample structure>

for Circuit filling test by quick-press



[Circuit filling test pattern]
L/S=50/50 to 100/100



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The data in this document are measured values, not for guaranteed.